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United States Patent [19]

Kawachi

[11] **Patent Number: Des. 404,369**

[45] **Date of Patent: **Jan. 19, 1999**

[54] **MANIFOLD COVER FOR USE IN A SEMICONDUCTOR WAFER HEAT PROCESSING APPARATUS**

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[73] Assignee: **Tokyo Electron Limited**, Tokyo-to, Japan

[**] Term: **14 Years**

[21] Appl. No.: **82,981**

[22] Filed: **Feb. 2, 1998**

[30] **Foreign Application Priority Data**

Aug. 20, 1997 [JP] Japan 9-65097

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; D15/144, D15/144.1, 199; 414/935–941, 217, 147; 437/247, 946

[56] **References Cited**

U.S. PATENT DOCUMENTS

4,857,689	8/1989	Lee	414/935 X
5,314,574	5/1994	Takahashi	414/935 X
5,320,218	6/1994	Yamashita et al.	414/935 X
5,752,796	5/1998	Muka	414/935 X

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[57] **CLAIM**

I claim the ornamental design for a manifold cover for use in a semiconductor wafer heat processing apparatus, as shown and described.

DESCRIPTION

FIG. **1** a perspective view of a cover manifold cover for use in a semiconductor wafer heat processing apparatus;

FIG. **2** a front elevational view thereof;

FIG. **3** a rear elevational view thereof;

FIG. **4** a top plan view thereof;

FIG. **5** a bottom plan view thereof;

FIG. **6** a right side view thereof;

FIG. **7** a left side view thereof; and,

FIG. **8** a cross-sectional view taken along line VIII-VIII in FIG. **2**.

1 Claim, 2 Drawing Sheets

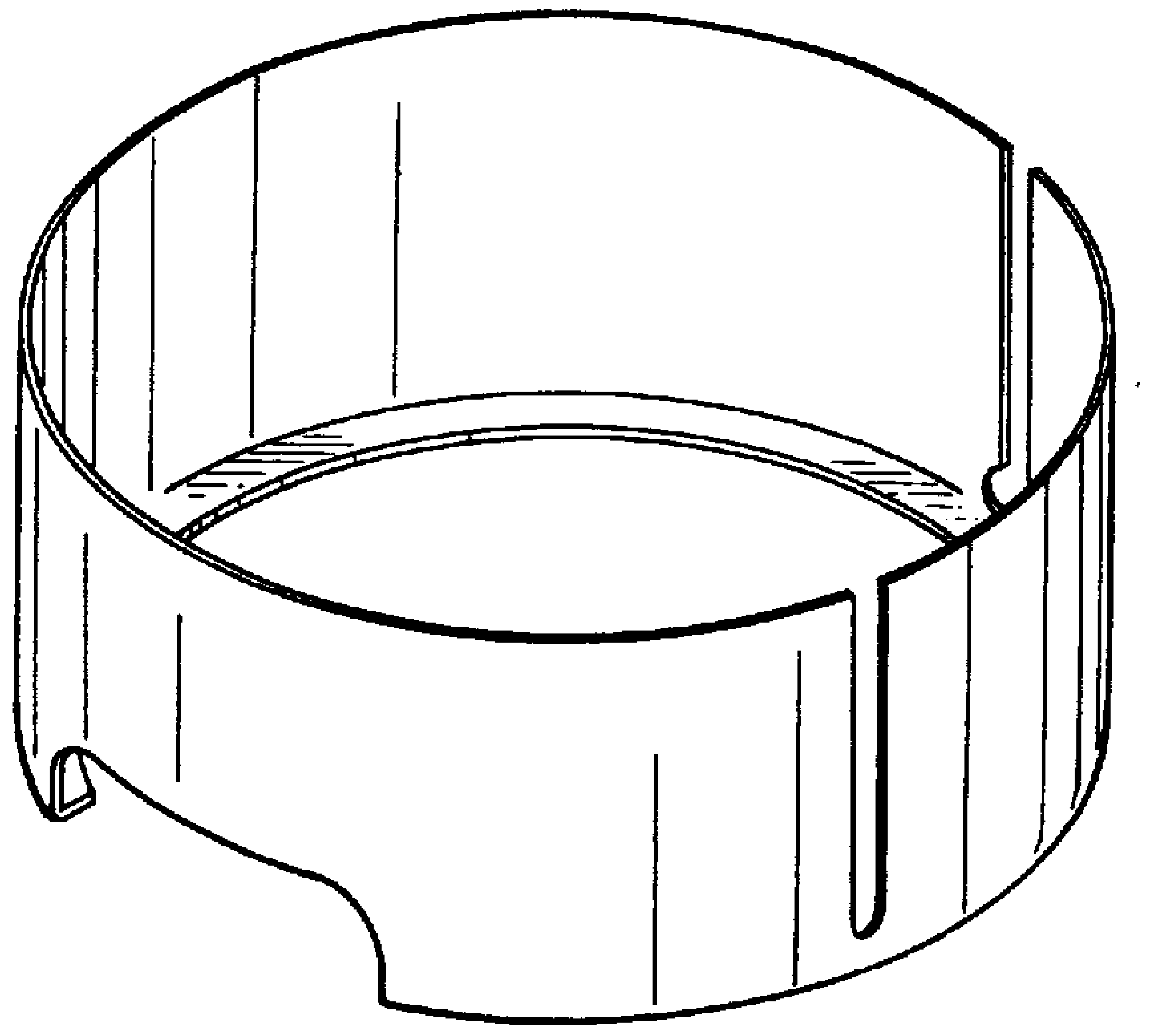

FIG. 1

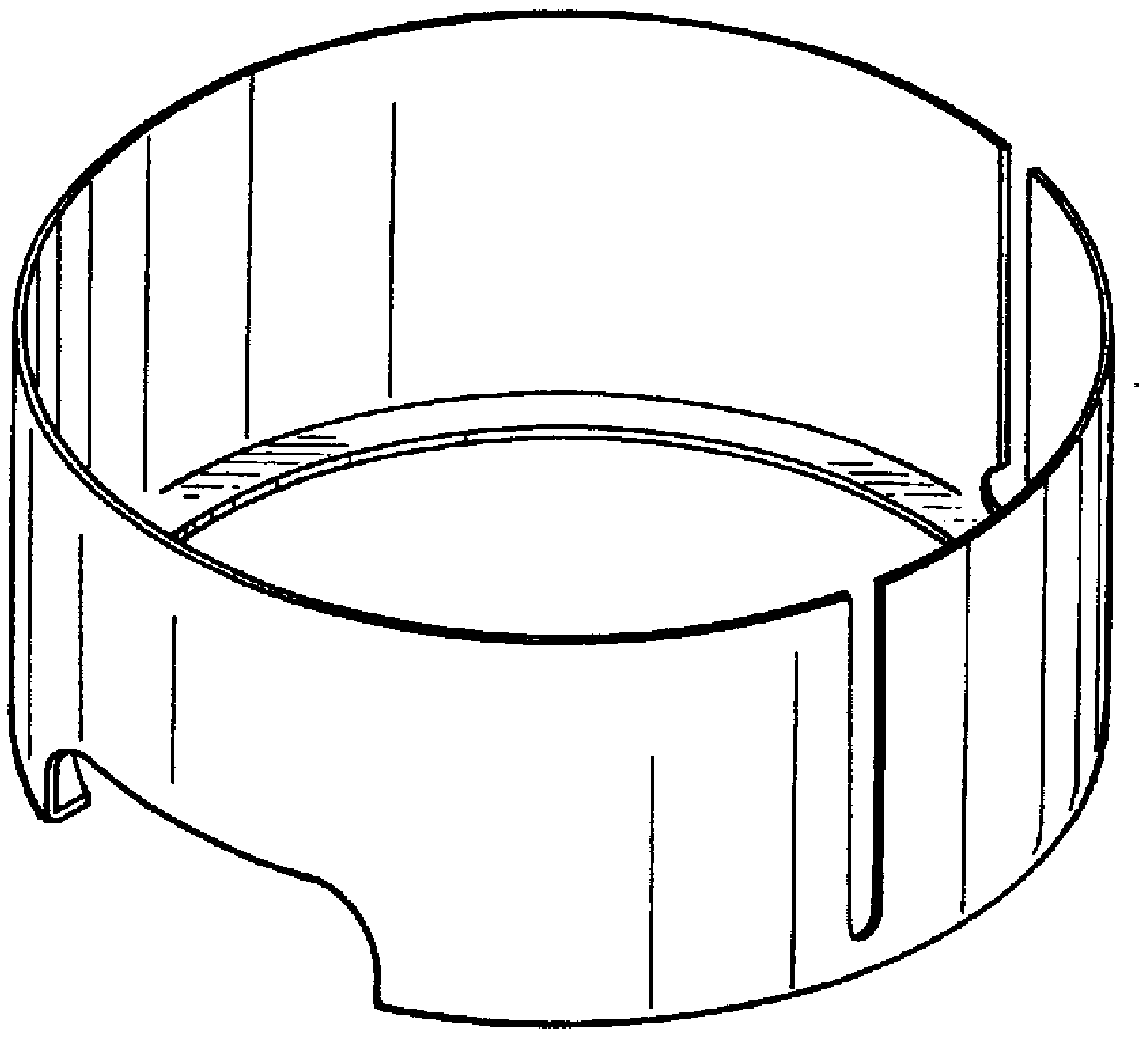

FIG. 2

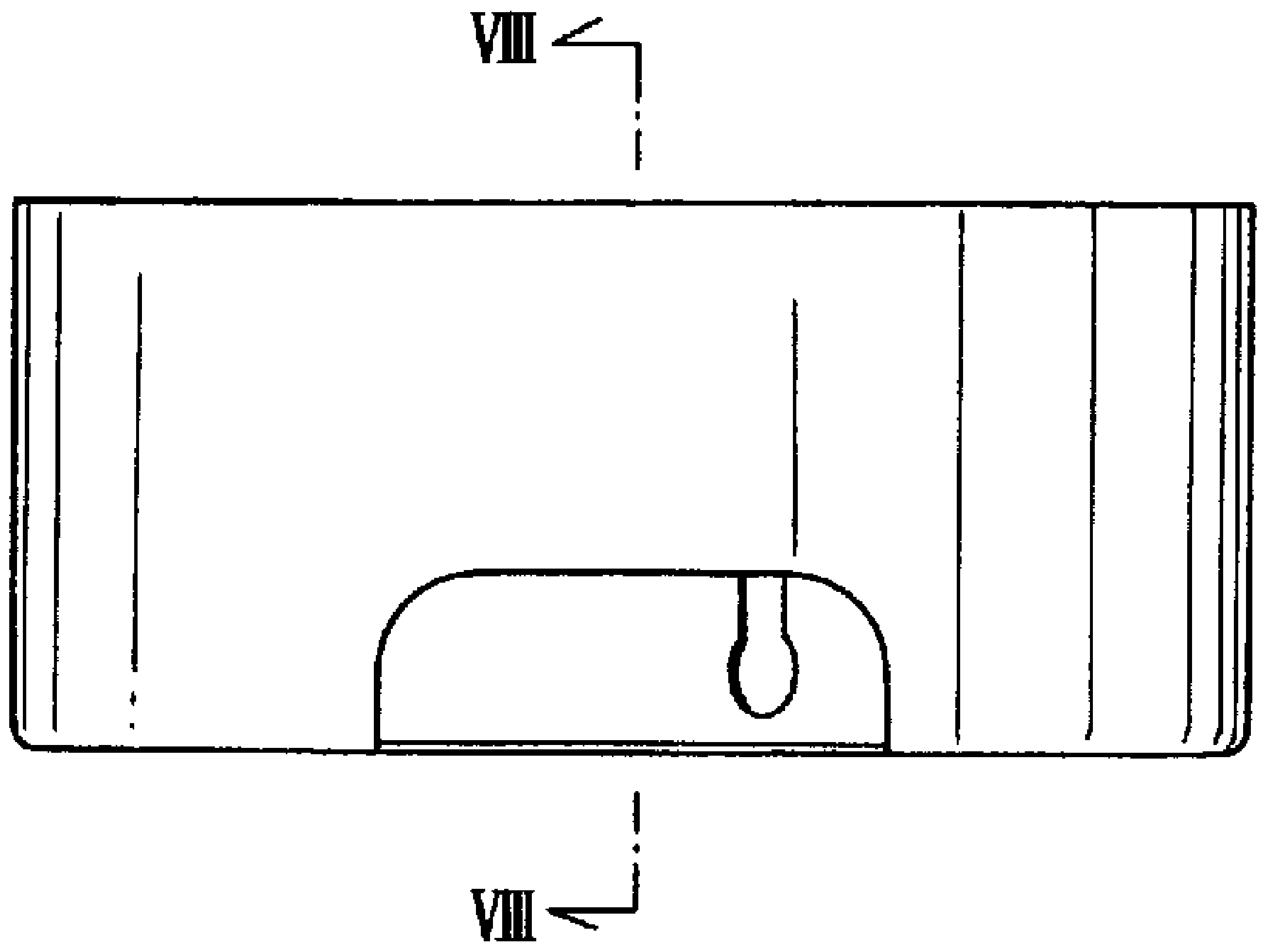

FIG. 3

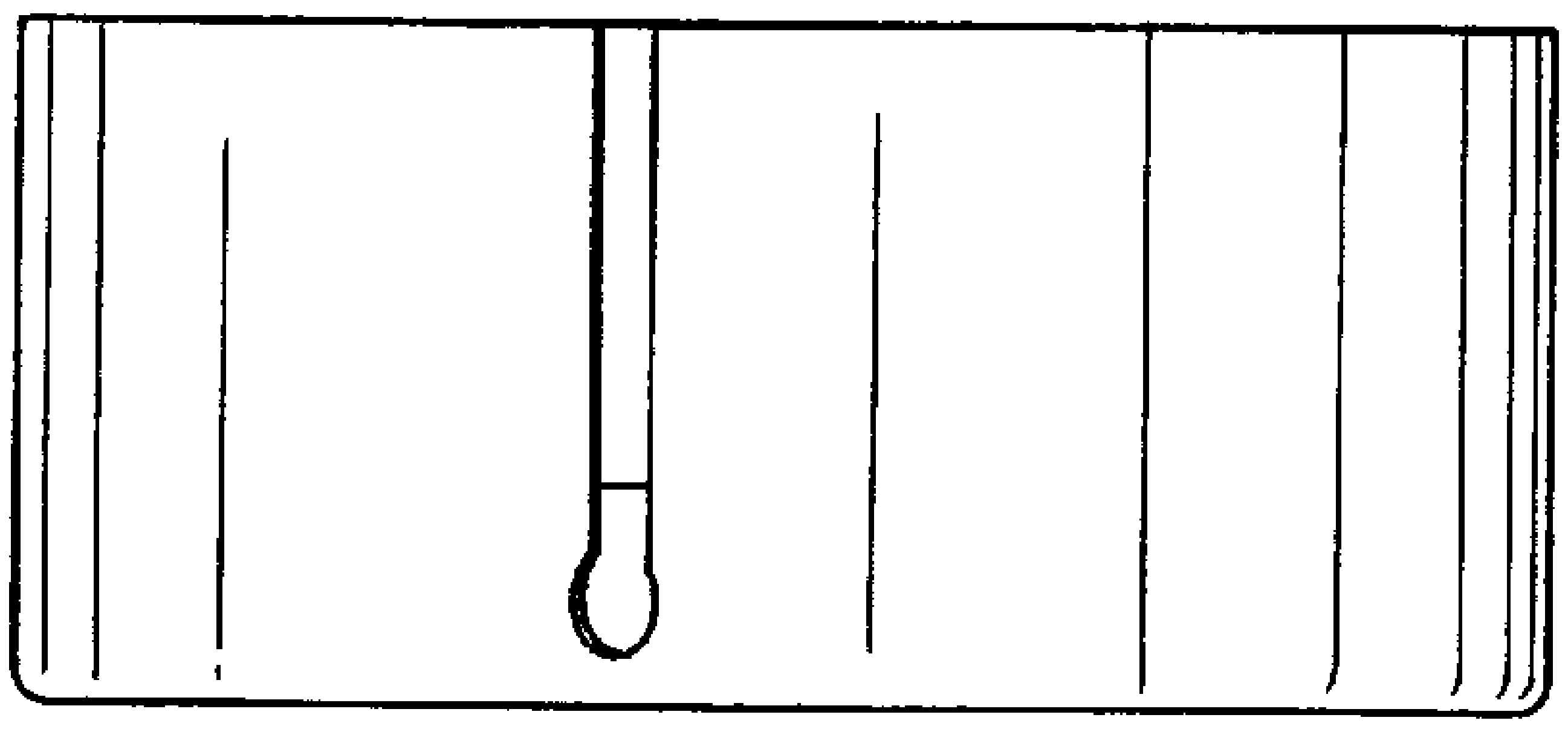

FIG. 4

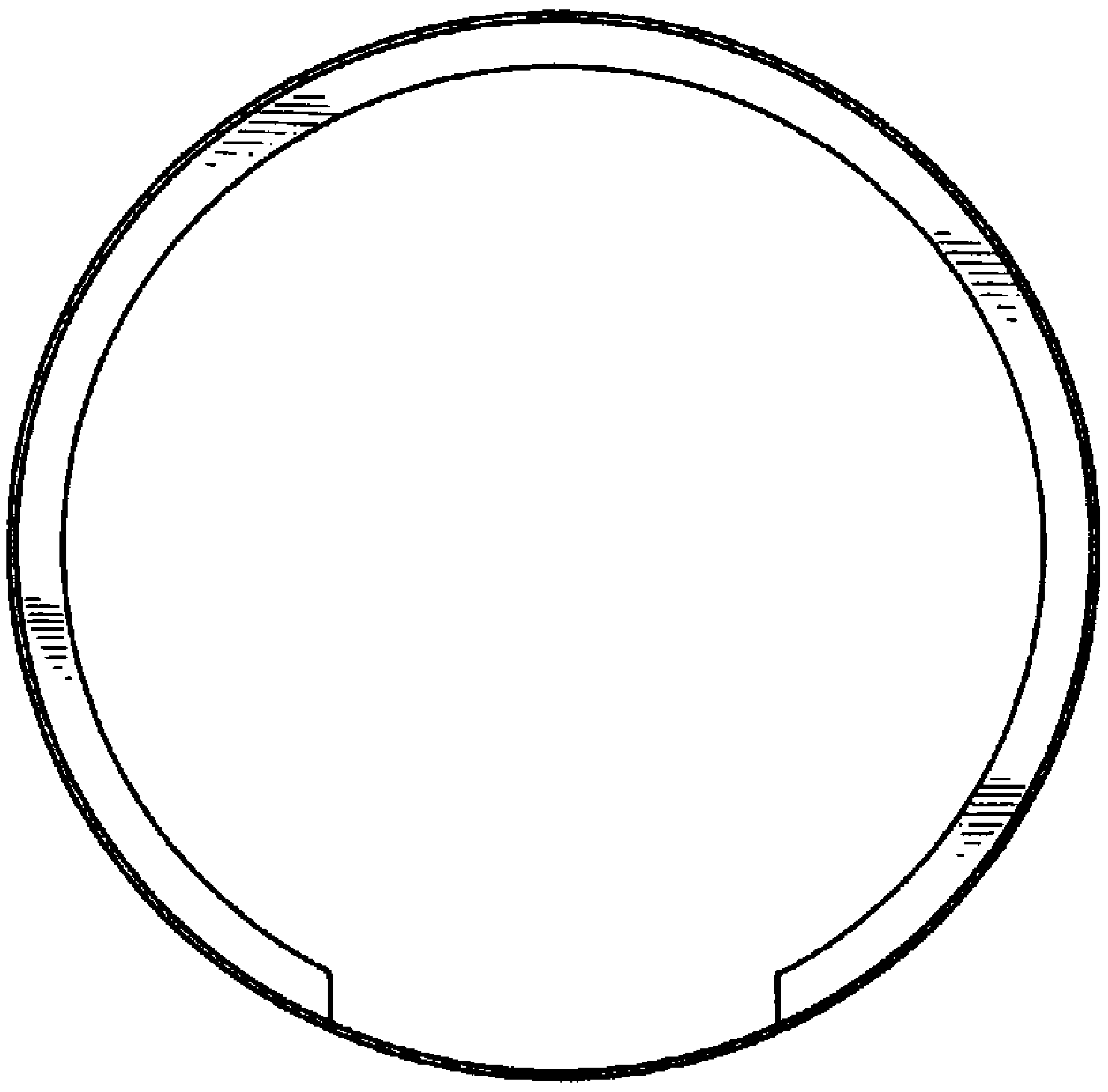

FIG. 5

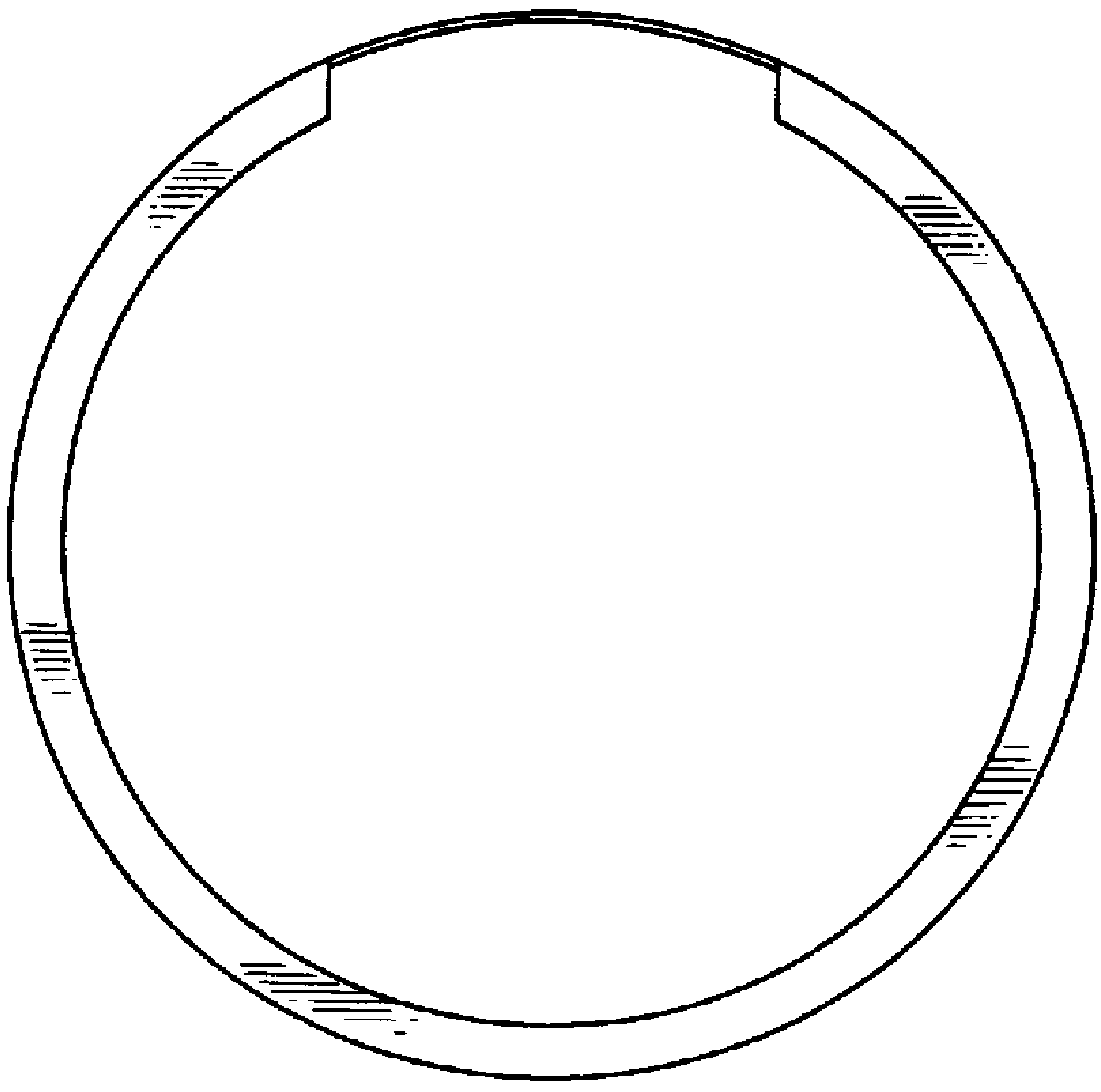

FIG. 6

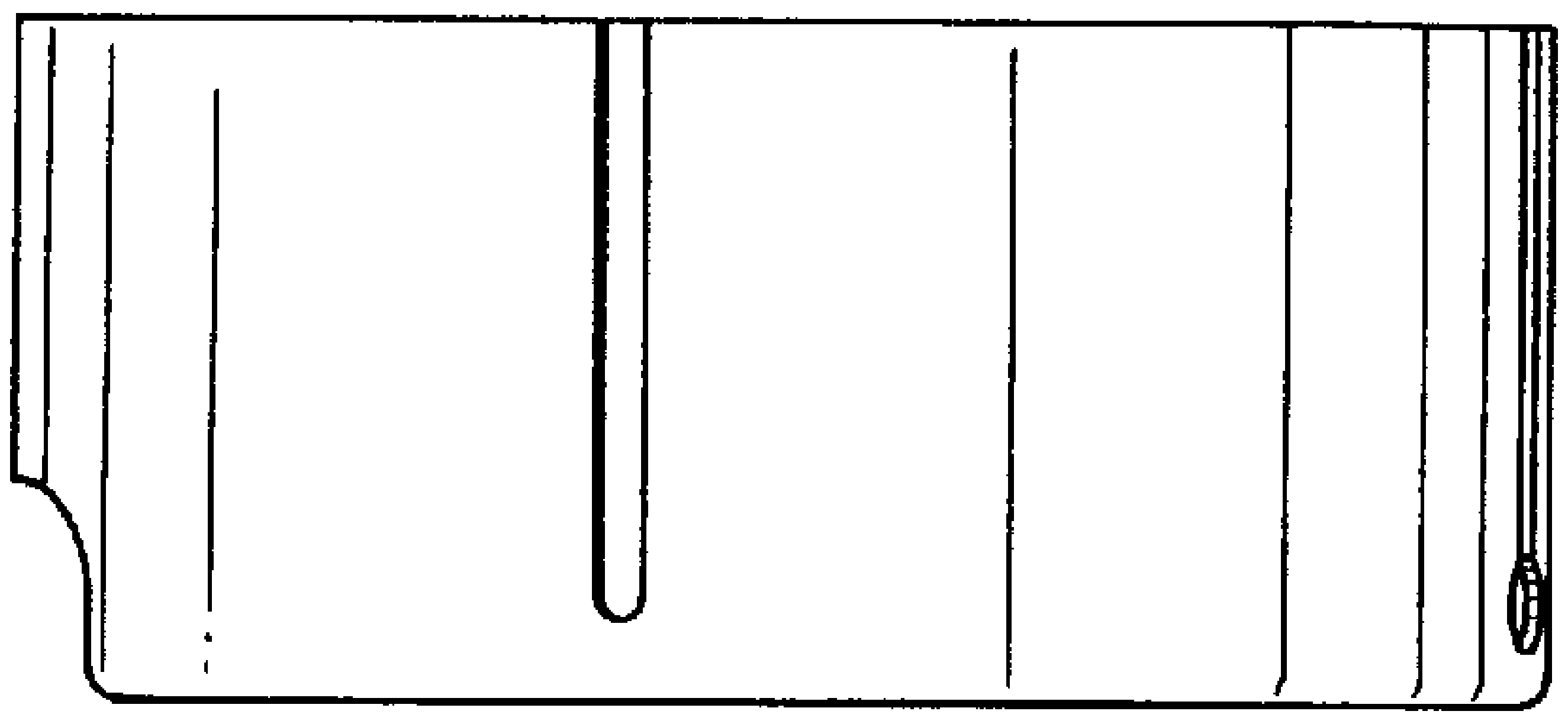

FIG. 7

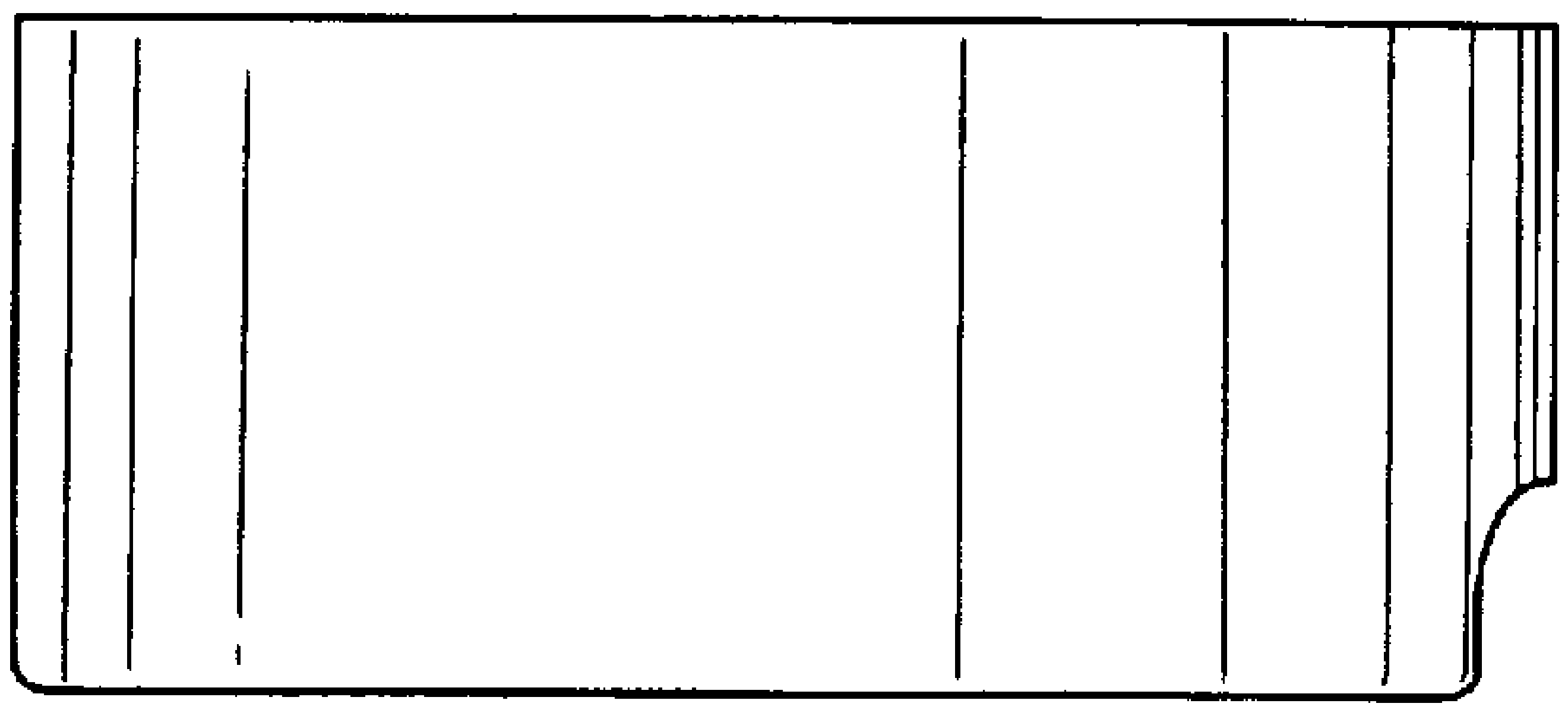

FIG. 8